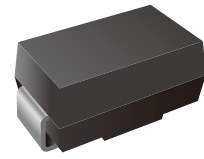


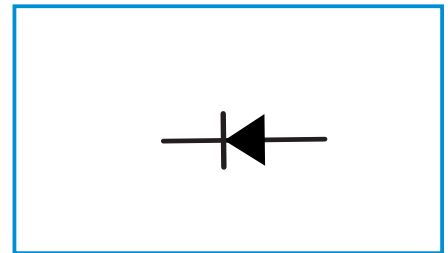
Surface Mount Schottky Barrier Rectifier



Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Marking: 2L100

Functional Diagram



Mechanical Data

- **Case:** JEDEC DO-214AC molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any
- **Weight:** 0.002 ounce, 0.07 grams

Maximum Ratings and Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

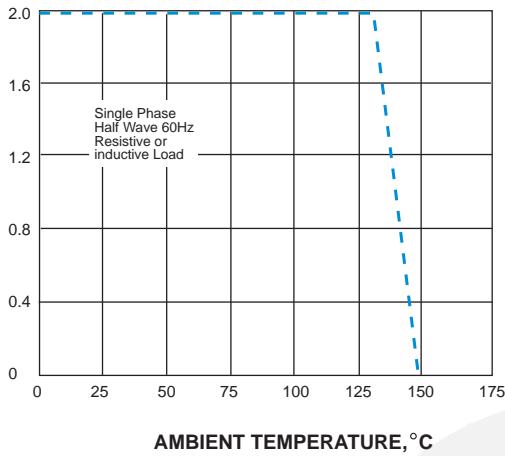
	SYMBOLS	LT2A100L	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	100	VOLTS
Maximum RMS voltage	V_{RMS}	70	VOLTS
Maximum DC blocking voltage	V_{DC}	100	VOLTS
Maximum average forward rectified current at T_L (see fig.1)	$I_{(AV)}$	2.0	Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	130.0	Amps
Maximum instantaneous forward voltage at 2.0A	V_F	0.79	Volts
Maximum DC reverse current at rated DC blocking voltage	I_R	$T_A=25^\circ C$ 0.008	mA
		$T_A=100^\circ C$ 5.0	
Typical junction capacitance (NOTE 1)	C_J	180	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0	°C/W
Operating junction temperature range	T_J	-65 to +150	°C
Storage temperature range	T_{STG}	-65 to +150	°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings and Characteristics Curves

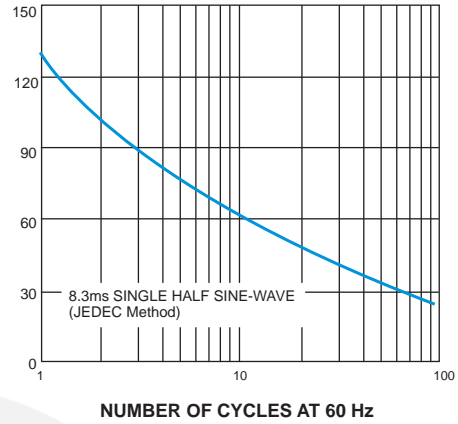
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



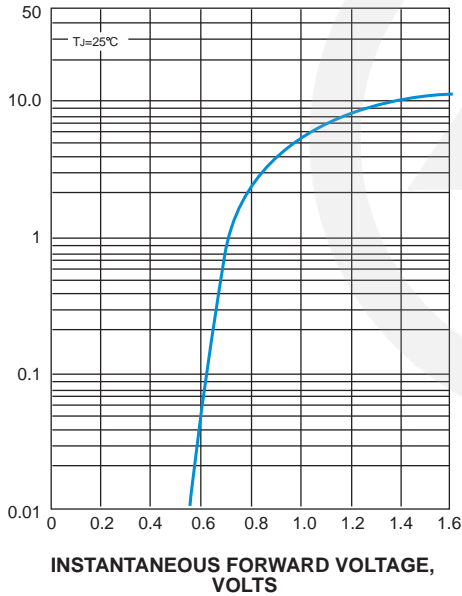
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



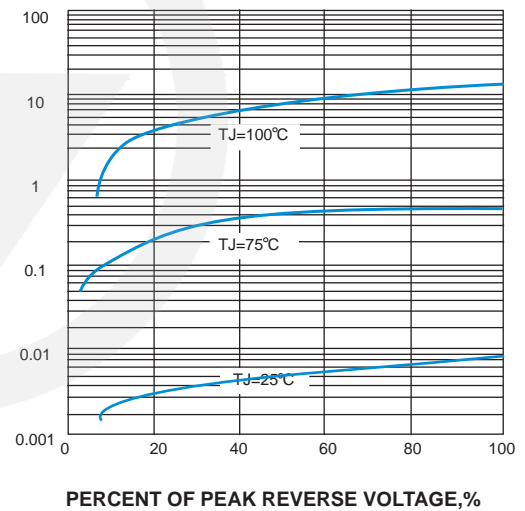
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



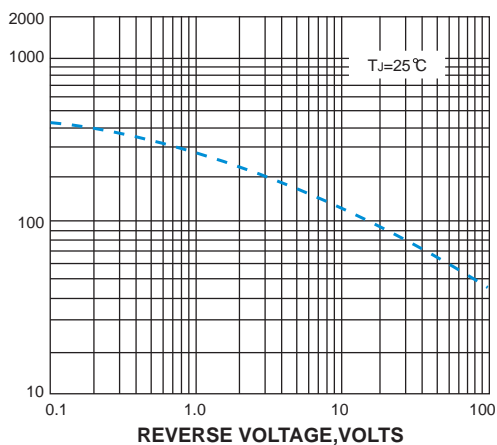
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



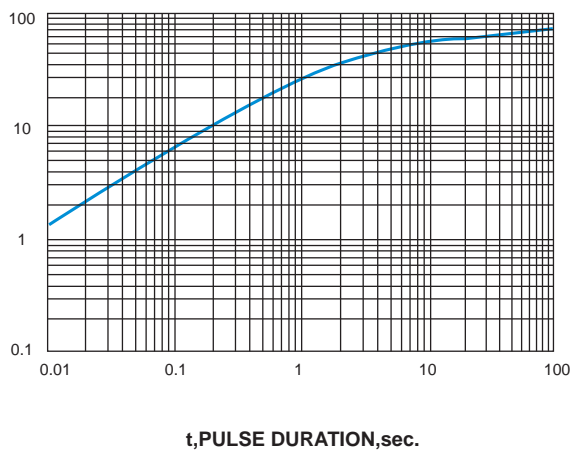
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE

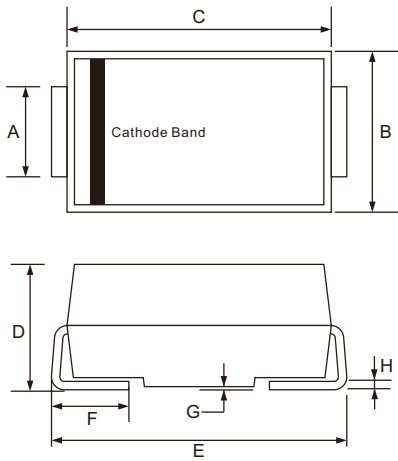


TRANSIENT THERMAL IMPEDANCE, °C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



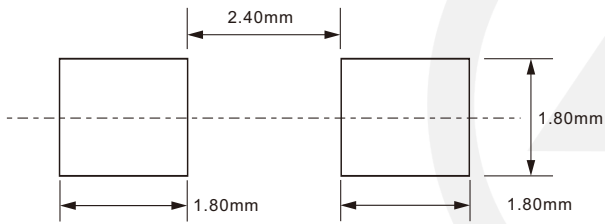
SMA Package Outline



Unit : mm

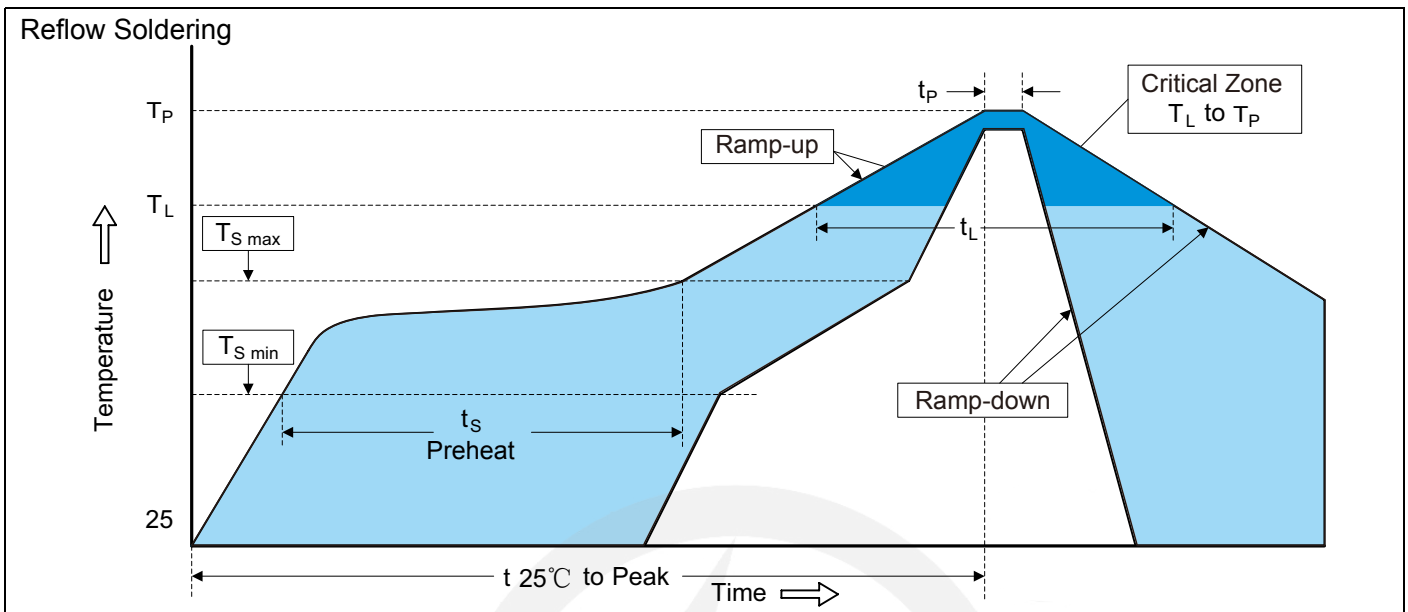
SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.25	1.65
B	2.30	2.79
C	4.00	4.75
D	1.90	2.50
E	4.70	5.28
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

SMA Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Recommended Soldering Conditions

Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

13" Reel


 D5 $\Phi 330.0 \pm 2.0$

 D6 $\Phi 13.5 \pm 0.5$

 H 2.5 ± 1.0

 W2 16.0 ± 2.0

Quantity: 5000PCS